

EVG announces NanoCleave layer release technology revolutionizing 3D Integration – January 30, 2024

EVG introduced NanoCleave[™], a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory and power device formation, as well as semiconductor advanced packaging. In 3D integration, carrier technologies for thin-wafer processing are key to enabling higher performance systems with increasing interconnection bandwidth. Glass carriers have become an established method for building up device layers through temporary bonding with organic adhesives, using an UV wavelength laser to dissolve the adhesives and release the device layers, which are subsequently permanently bonded onto the final product wafer. However, glass substrates are difficult to process with semiconductor fab equipment that have been designed primarily around silicon, and that require costly upgrades to enable glass wafer processing. In addition, organic adhesives are generally limited to processing temperatures below 300°C, which limits their use to backend processing.

쇼신소재경제





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